

WHAT IS CLAIMED IS:

1. A high-frequency package comprising:

a dielectric substrate, on one face of which a mounting portion of a high-frequency circuit component is formed;

a first line conductor, formed on the one face of the dielectric substrate from a vicinity of the mounting portion in an outer periphery direction, for transmitting high-frequency signals;

a first coplanar grounding conductor formed on both sides of the first line conductor on the one face of the dielectric substrate;

a second line conductor, formed on another face of the dielectric substrate toward an outer periphery edge so that an end portion thereof faces an outer-periphery-side end portion of the first line conductor, for transmitting the high-frequency signals;

a second coplanar grounding conductor formed on both sides of the second line conductor on the other face of dielectric substrate;

a through conductor, formed inside the dielectric substrate, for electrically connecting the facing end portions of the first and second line conductors;

a grounding through conductor, formed inside the dielectric substrate, for electrically connecting the first and

second coplanar grounding conductors;

a metal terminal bonded to the second line conductor in parallel; and

grounding metal terminals bonded to the second coplanar grounding conductors on both sides of the metal terminal in parallel, respectively,

wherein a gap between the grounding metal terminals is equal to or less than one half of a wavelength of the high-frequency signals.

2. The high-frequency package of claim 1, wherein a conductor non-formed portion is disposed on a region in the first coplanar grounding conductor corresponding to a position of the metal terminal.

3. The high-frequency package of claim 2, wherein a width of the non-formed portion is equal to a width between the grounding metal terminals.

4. The high-frequency package of claim 2, wherein a width of the non-formed portion is equal to or less than 80 % of a width between the grounding metal terminals.

5. The high-frequency package of claim 2, wherein a shape

of the non-formed portion is a circle or an oval.

6. The high-frequency package of claim 1, wherein the metal terminal is placed on a side of an outer periphery of the dielectric substrate.

7. The high-frequency package of claim 1, wherein a castellated grounding conductor that electrically connects the first coplanar grounding conductor and the grounding metal terminal is disposed on a region in a side face of the dielectric substrate corresponding to a position of the grounding metal terminal.